July 16, 2025
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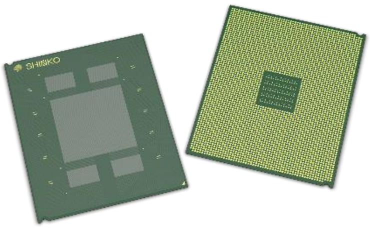
SHINKO ELECTRIC INDUSTRIES CO., LTD.

SHINKO ELECTRIC INDUSTRIES CO., LTD. Acquires IATF 16949 Certification for Flip-Chip Type Packages

NAGANO, Japan, July 16, 2025 – SHINKO ELECTRIC INDUSTRIES CO., LTD. (SHINKO) announced acquiring IATF 16949 certification, an international quality management system standard for the automotive industry, at Kohoku and Wakaho Plants, both located in Nagano City, for the design and manufacturing of flip-chip type packages for CPUs and GPUs.

Automotive semiconductors are in high demand as key components in car electronics, and SHINKO's flip-chip type packages are used as highly dependable package substrates for automotive semiconductors. As the spread of ADAS (Advanced Driver-Assistance Systems) and autonomous driving technology, etc., package substrates which respond to advancement of higher speed and higher density of CPUs and GPUs will become important even more in the future, so it is essential to provide products with high reliability and to further improve their quality. To meet the quality requirements of our customers, SHINKO has promoted the introduction of a quality management system based on IATF 16949 and, as a result of efforts to acquire this standard, has been certified.

IATF 16949 is an international standard for automotive industry-specific quality management systems, based on ISO 9001, with stringent requirements unique to the automotive industry. This standard has been adopted as the global procurement standard for automotive components by many automobile manufacturers and suppliers to the automotive industry worldwide. Through this certification, SHINKO is committed to continuous quality improvement and a stable supply of high-quality products for all customers.



Flip-Chip Type Packages

Certification details

1) Registration standard : IATF16949-First Edition
2) Certification authority : Bureau Veritas Certification Holding
3) IATF Certification number : Kohoku Plant 0575619
Wakaho Plant 0575676

4) Certification authority certificate number : Kohoku Plant JP026388-1 - IATF
Wakaho Plant JP026388-2 - IATF

5) Original approval date : June 17, 2025

6) Certified organization :
SHINKO ELECTRIC INDUSTRIES CO., LTD. Plastic Laminated Package Div.I Kohoku Plant.
SHINKO ELECTRIC INDUSTRIES CO., LTD. Plastic Laminated Package Div.I Wakaho Plant.

7) Scope of certification : Design and manufacturing of Substrate for IC package.

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President's Office

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